



Device Material Content

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Package: 484 caBGA
Total Device Weight 1.030 Grams

Package Code:

BG484

Products:

LCMX03D-9400

Assembly: ATK

Size (mm): 19 x 19

Lead pitch (mm): 0.8

MSL: 3

Reflow max (°C): 260

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	2.07%	0.0213			Silicon chip	7440-21-3	100.00%	Die size: 5.23 x 6.26 x 0.279 mm
Mold Compound	47.25%	0.4869	1.42%	0.01461	Epoxy Resin A	-	3.00%	Mold Compound: Sumitomo EME G770SFE
			1.42%	0.01461	Epoxy Resin B	-	3.00%	
			1.42%	0.01461	Phenol Resin	-	3.00%	
			34.26%	0.35300	Silica, vitreous	60676-86-0	72.50%	
			7.09%	0.07303	Silicon dioxide	7631-86-9	15.00%	
			1.42%	0.01461	Aluminium and its compounds	-	3.00%	
			0.24%	0.00243	Carbon Black	1333-86-4	0.50%	
D/A Epoxy	0.35%	0.0036	0.30%	0.00307	Silver	7440-22-4	85.00%	Die attach epoxy: Henkel QMI-529HT
			0.04%	0.00036	Isobornyl Methacrylate	7534-94-3	10.00%	
			0.02%	0.00018	Bismaleimide Resin	-	5.00%	
Wire	0.34%	0.0035	0.33%	0.00340	Copper (Cu)	7440-50-8	97.05%	Au coated PCC, 0.02mm dia
			0.01%	0.00010	Palladium (Pd)	7440-05-3	2.80%	
			0.00%	0.000005	Gold (Au)	7440-57-5	0.15%	
Solder Balls	16.60%	0.1711	16.02%	0.1651	Tin (Sn)	7440-31-5	96.50%	MKE SAC305
			0.50%	0.00513	Silver (Ag)	7440-22-4	3.00%	
			0.08%	0.00086	Copper (Cu)	7440-50-8	0.50%	
Substrate	15.67%	0.1615	4.31%	0.0444	BT Resins	-	27.50%	BT Resin CCL-HL832NX-A* 2 layer
			4.31%	0.0444	Inorganic filler	21645-51-2	27.50%	
			7.05%	0.0727	Glass fiber	65997-17-3	45.00%	
Solder mask	2.07%	0.0213	1.56%	0.01610	Resin	-	75.50%	Solder mask PSR4000 AUS 320
			0.00%	0.00004	Phthalocyanine blue	147-14-8	0.20%	
			0.00%	0.00004	Organic pigment	-	0.20%	
			0.01%	0.00011	Silica	-	0.50%	
			0.43%	0.00444	Barium sulfate	7727-43-7	20.80%	
			0.04%	0.00045	Talc	14807-96-6	2.10%	
			0.01%	0.00015	Antifoamer and Leveling agent	-	0.70%	
Foil	15.65%	0.1613	8.47%	0.0872	Copper	7440-50-8	54.10%	
			5.90%	0.0608	Nickel plating	7440-02-0	37.69%	
			1.28%	0.0132	Gold plating	7440-57-5	8.17%	

Notes: * 0.16% max. concentration of Bisphenol A (CAS# 80-05-7) in substrate laminate material as impurity - not intentionally added.

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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